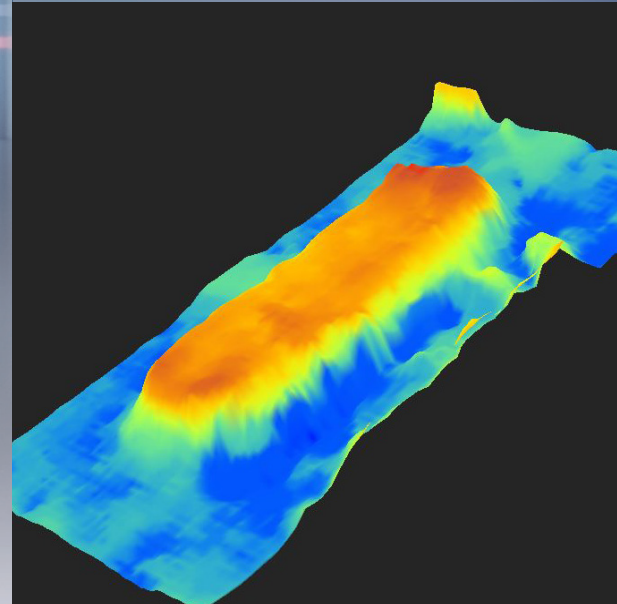




Solder Paste Inspection System (SPI) for In-Line Manufacturing



iS6052 SPI

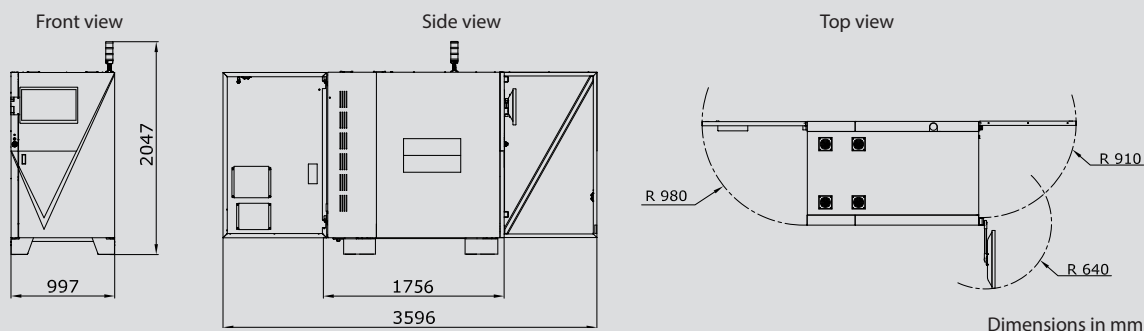
Economical technology for reliable solder and
sinter paste inspection

3D SPI



Technical Specifications

iS6052 SPI



iS6052 SPI

Inspection Scope		Solder paste deposits (stencil printing or dispensing technology, up to pad sizes for 01005 components); sinter paste, adhesives, surface, height, print displacement, smearing, shape, coplanarity, open area analysis, OCR, DMC
Camera technology		XM SPI
3D Sensor Technology		
Z-resolution		0,1 µm
Z-range		Up to 5mm
Angled view cameras		
Number of megapixel cameras		4
Orthogonal camera		
Resolution		12 µm
Field of view		58 mm x 58 mm (2.2" x 2.2")
Inspection Speed		Up to 80 cm ² /s
Software		
User interface		Viscom vVision
Statistical process control		Viscom vSPC/SPC, open interface (optional)
Verification station		Viscom vVerify
Remote diagnosis		Viscom SRC (optional)
Programming station		Viscom PST34 (optional)
System computer		
Operating system		Windows®
Processor		Intel®Core™i7
PCB handling		
PCB dimensions		508 mm x 508 mm (20" x 20")
PCB support		Optional
Transport height		900 - 950 mm ± 20 mm (35.4" - 37.4" ± 0.8")
Width adjustment		Automatic
Transport concept		Single-track transport system, dual-lane option available
PCB clamping		Pneumatic
Upper transport clearance		50 mm (2")
Lower transport clearance		50 mm (2"); 40 mm (1.6") with PCB support
Other system data		
Positioning unit		Synchronous linear motor
Interfaces		SMEMA, Hermes
Power requirements		230/400 V, 50 Hz, 3P/N/PE +/- 10%; 4 - 6 bar working pressure
System dimensions		997 mm x 1756 mm x 1753 mm (39.3" x 69.1" x 69") (W x D x H)
Weight		Approx. 1060 kg (2337 lbs)